Celanese
The chemistry inside innovation™

HOSTAFORM® HL100

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- High viscosity friction & wear polyacetal homopolymer
- non-silicon type special polymer modified wear-friction resistance grade for injection molding
- Designed for applications requiring reduced wear, low friction and low nois.

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt mass-flow rate	2.2	g/10min	ISO 1133
Melt mass-flow rate, Temperature	190	°C	
Melt mass-flow rate, Load	2.16	kg	
Moulding shrinkage, parallel	2.1	%	ISO 294-4, 2577
Moulding shrinkage, normal	0	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2700	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	65	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	20	%	ISO 527-1/-2
Nominal strain at break	43	%	ISO 527-1/-2
Flexural modulus	2580	MPa	ISO 178
Flexural strength	86	MPa	ISO 178
Charpy impact strength, 23°C	N	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	8.9	kJ/m²	ISO 179/1eA
Poisson's ratio	0.38[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	177	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	100	°C	ISO 75-1/-2

Physical/Other properties

Density	1410	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	205	°C
Min. melt temperature	190	°C
Max. melt temperature	220	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	70	°C
Min. mould temperature	60	°C
Max. mould temperature	80	°C
Hold pressure range	60 - 120	MPa

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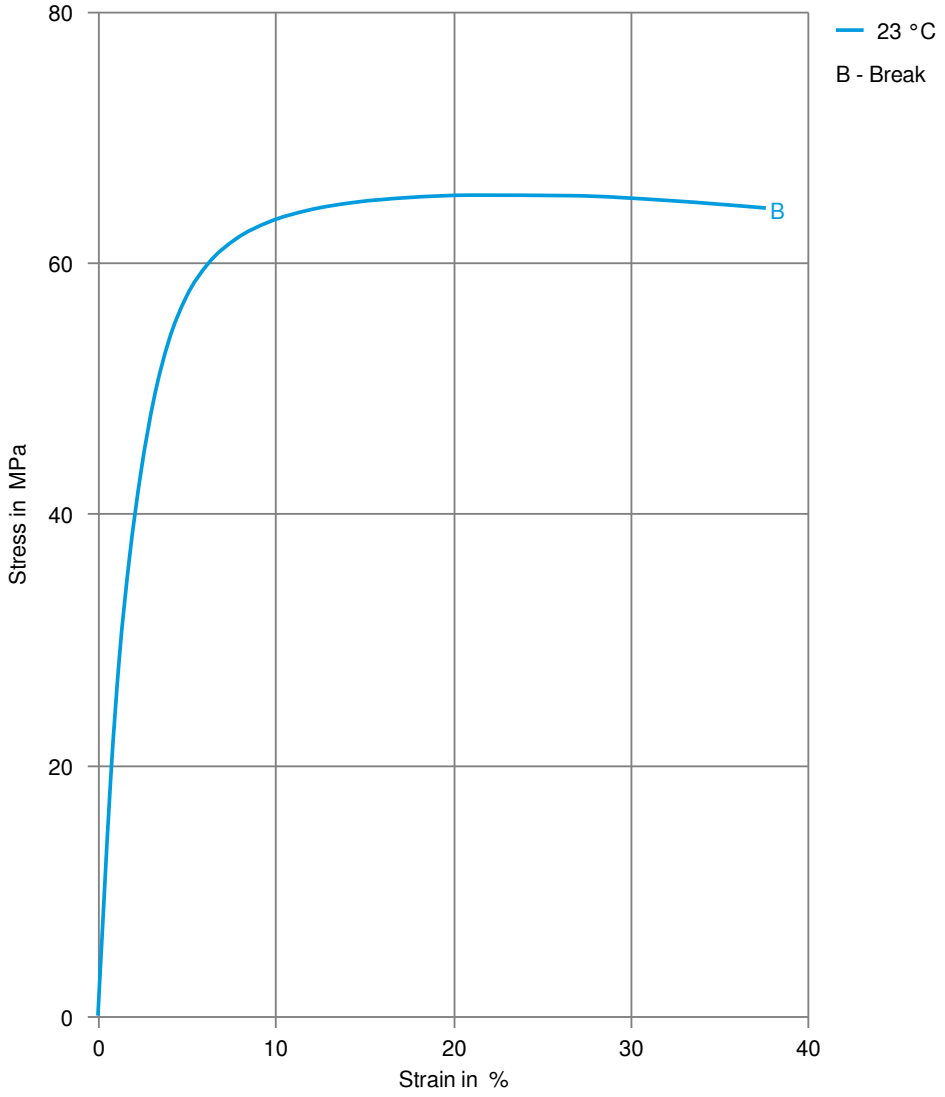
Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Special characteristics	Low wear / Low friction

Stress-strain



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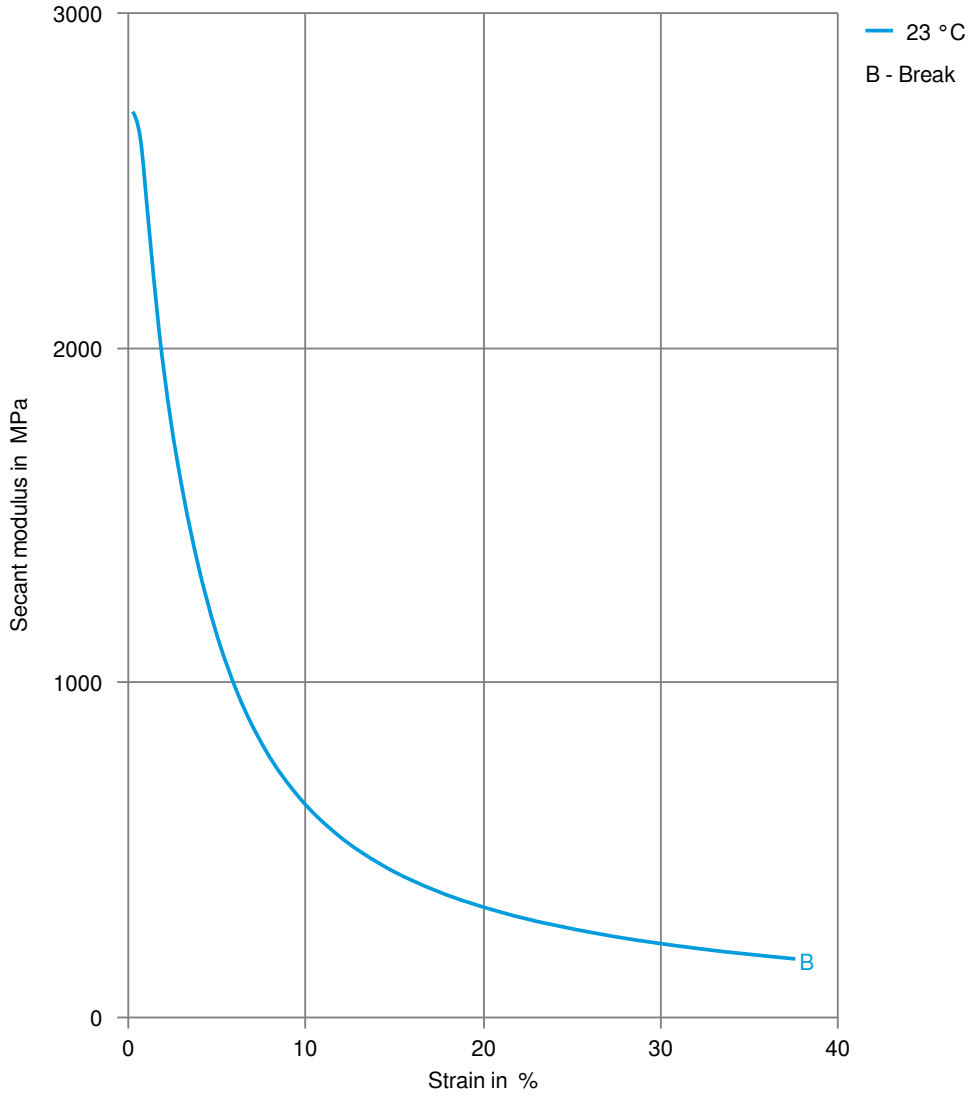
Secant modulus-strain



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